OL

Introduction

OL is a lower profile, Grade 3 copper foil designed specifically for outer layer applications on Multilayer Printed Circuits. OL copper foil is supplied with a TOB treatment which is fully compatible with all epoxy resin systems.

Benefits

- Lower profile for fine lines with consistent etching
- Excellent handling characteristics
- Superior drilling characteristics
- Consistent drilling characteristics

Typical Physical Characteristics

Oak-Mitsui foils meet all requirements of IPC-4562 and are produced with the patented "AT" resin resistant treatment.

Nominal Thickness Area Weight		microns oz/ft²	18 1/2	35 1	70 2
Tensile	ambient 180ºC	Kpsi Kpsi	60 30	55 30	52.5 30
Elongation	ambient 180ºC	%E %E	8 4	15 5	20 5
Roughness	drum matte	Ra Rmax	10 200	10 300	10 450
Peel Strength B Epoxy, Tg 170ºC	matte	lbs/in	7.5	10.5	15

The information contained in this specification is not intended to and does not create any warranties, express or implied, including any warranty of merchantability or fitness for a particular purpose. The actual performance of Mitsui materials will vary according to the customer's application.